

Spray Solvent Tool Demo Request Form

Date of Request: _____
 Requestor's Name: _____
 Requestor's E-mail: _____
 Requestor's Phone: _____
 ClassOne Sales Person's Name: _____
 ClassOne Sales Person's E-mail: _____
 ClassOne Sales Person's Phone: _____

Instructions

1. Complete this Demo Request Form as fully as possible.
2. Submit completed form to your sales representative, or email to demo@classone.com.
3. You will be contacted by a technical representative from ClassOne to discuss your request in detail.
4. Based upon the details of your request, and availability of required resources, a date will be set for your demo.

Samples/Materials Return Address

Company: _____
 Attention: _____
 Address: _____

 City / State: _____

Customer's Preferred Shipper: _____
 Customer's Shipping Account Number: _____
 Shipping Method:
 Priority Overnight Overnight 2nd Day 3rd Day
 Ground Other: _____

- Please return any excess materials to us at our expense.
- Please dispose of any excess materials at our expense.

Shipping Notes:

Product Application

Please describe the product(s) that the demo sample will be used in, e.g., printers, memory, etc.

Demo Description

Check all that apply:

- | | | | |
|---|--|---|---|
| <input type="checkbox"/> Bulk Stock Removal | <input type="checkbox"/> Polymer Removal | <input type="checkbox"/> Stress Relief/Etch | <input type="checkbox"/> Metal Replating/Deposition |
| <input type="checkbox"/> Metal Lift Off | <input type="checkbox"/> Resist Develop | <input type="checkbox"/> Under-Bump Metalurgy | <input type="checkbox"/> Other: _____ |
| <input type="checkbox"/> Metal Etch | <input type="checkbox"/> Resist Removal | <input type="checkbox"/> Via/Line Clean | _____ |
| <input type="checkbox"/> Oxide Etch | <input type="checkbox"/> Spin Rinse Dry | <input type="checkbox"/> Wafer Reclaim | _____ |

Please describe the current process:

Success Criteria

What measurements or qualities will be used to judge demo success? Be as specific as possible. Demos cannot be run without success criteria.

Control Factors

Number of Wafers: _____ Patterned Unpatterned
Wafer Diameter: _____ Orientation: _____ Thickness: _____
Surface Nature: _____
Previous Process Step: _____
Front-side Protection (film type): _____
Photoresist Type: Pos Neg Thickness: _____
Bake Method: _____
Device Geometry: _____
Film to be Etched: _____
Thickness Removal: _____
Metal Types: _____ Thickness of Each Metal: _____
Electronic Endpoint Detection? Yes No
Mask Materials: PR Film Metal
Non-target Films Present: _____
Chemistry Requested / Used: _____

Other Information

Please include any other information relevant to this Demo Request in the space below:

Shipping to ClassOne

Critical Information, Please Note:

- Do not ship your materials to ClassOne before receiving a Demo Number.
- The Demo Number is the only way we can guarantee your materials will be properly tracked.
- Each package must have the Demo Number clearly displayed.
- All wafer carriers should be double-bagged.

Ship To:

ClassOne Technology
Attn: Applications Lab
5302 Snapfinger Woods Drive
Decatur, GA 30035 USA
Tel: + 1 (770) 808-9706